Semiconductor Device Type: (NCA) 016 VQFN 3x3x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling
										e4
		"Contained In"	% Total			8.64	(mg) Total	Mold Compound	% ot Total Weight	40.57
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm				5	
Silica, fused	60676-86-0	Mold Compound	36.513	7.777	365,130		Silica, fused	60676-86-0	90.00	
Epoxy Resin Phenolic Resin	Trade Secret Trade Secret	Mold Compound Mold Compound	1.968 1.968	0.419	19,676 19.676		Epoxy Resin	Trade Secret Trade Secret	4.85	
Carbon Black	1333-86-4	Mold Compound Mold Compound	0.122	0.419	19,676		Phenolic Resin Carbon Black	1333-86-4	4.85	
	7440-50-8	Lead Frame	-	11.003	,		Carbon Black	1333-86-4 Total	0.30	
Copper Iron	7439-89-6	Lead Frame	51.657 1.221	0.260	516,566 12,211	44.04	(50.00
					1	11.31	(mg) Total	Lead Frame	% of Total Weight	53.09
Phosphorous	7723-14-0 7440-66-6	Lead Frame	0.133	0.028	1,327 796		Copper	7440-50-8	97.30	
Zinc (Metal) Silver	7440-66-6	Lead Frame Die Attach	0.080	0.017 0.110	796 5,166		Iron	7439-89-6	2.30	
Sliver Epoxy Resin	9003-36-5	Die Attach Die Attach	0.517	0.110	5,166		Phosphorous Zipa (Motal)	7723-14-0 7440-66-6	0.25 0.15	
Silicon	7440-21-3	Chip (Die)	3.300	0.039	33.000		Zinc (Metal)	7440-66-6 Total	0.15	l
Gold	7440-21-3	Wire Bond	0.500	0.103	5,000	0.15	(Die Attach	% of Total Weight	0.70
Nickel	7440-02-0	Plating on external leads (pins)	1.656		16.560	0.15	(mg) Total	7440-22-4		0.70
Palladium	7440-02-0	Plating on external leads (pins) Plating on external leads (pins)	0.092	0.353	920		Silver	7440-22-4 9003-36-5	73.80	
Gold	7440-03-3	°	0.092	0.020	920		Epoxy Resin	9003-36-5 Total	26.20 100.00	
Gold	7440-57-5	Plating on external leads (pins)				0.70	T = (= 1 (··· ··)			
		TOTALS:	100.000	21.300	1,000,000	0.70	Total (mg)	Chip (Die)	% of Total Weight	3.30
/EU (31 March 2015) and 2002/53/EC (End- nce with the above EU Directives has beer	aterials comply with -of-Life Vehicles (EL n verified via interna	design controls, supplier declarations, and /or	analytical test o	data.		0.11	Doped Silicon (mg) Total	Total Wire Bond	100.00 100.00 % of Total Weight	0.50
3/EU (31 March 2015) and 2002/53/EC (End- nce with the above EU Directives has beer nical substance is absent from the list abo ip Technology Incorporated's knowledge a	aterials comply with -of-Life Vehicles (EL n verified via internal ve, the chemical sub and belief as of the d	EU Directives: 2002/95/EC (27 January 2003) & /) without exemption (zero)	analytical test o emiconductor o n to believe tha	data. device and, to t t the unavoidal	he best of	0.11		Total	100.00	0.50
3/EU (31 March 2015) and 2002/53/EC (End- ance with the above EU Directives has been mical substance is absent from the list abov nip Technology Incorporated's knowledge a tration of the chemical substance, if any, is g compounds used by Microchip meet the U	laterials comply with -of-Life Vehicles (EL n verified via internal ve, the chemical sub and belief as of the d not below the thresi JL94 V0 flammability	EU Directives: 2002/95/EC (27 January 2003) & /) without exemption (zero) design controls, supplier declarations, and /or stance is NOT an intentional ingredient in the so ate of this document, there is no credible reason nold of regulatory concern for any regulatory so standard for plastics. You can access the UL io	analytical test o emiconductor o n to believe tha cheme world-wi	data. device and, to t t the unavoidal ide.	the best of ble impurity	0.11	(mg) Total	Total Wire Bond	100.00 % of Total Weight	0.50
3/EU (31 March 2015) and 2002/53/EC (End- ance with the above EU Directives has been mical substance is absent from the list abov hip Technology Incorporated's knowledge a tration of the chemical substance, if any, is g compounds used by Microchip meet the U tt http://ul.com/global/eng/pages/offerings/in tective "tubes" in which the specific produ- the outer box and certain "reels" may be ma	laterials comply wiff -of-Life Vehicles (EL n verified via internal ve, the chemical sub and belief as of the d not below the thresi JL94 V0 flammability ndustries/chemicals ct is shipped are ma ade from PVC plastic	EU Directives: 2002/95/EC (27 January 2003) & // without exemption (zero) design controls, supplier declarations, and /or stance is NOT an intentional ingredient in the s- ate of this document, there is no credible reason hold of regulatory concern for any regulatory sc standard for plastics. You can access the UL iC plastics/ de from polyvinyl chloride (PVC) plastic. "Windo 2.	analytical test of emiconductor of n to believe tha cheme world-wi QTM family of d ow envelopes"	data. device and, to t t the unavoidal ide. latabases to ob used to hold th	the best of ble impurity otain a test he packing	0.11	(mg) Total	Total Wire Bond 7440-57-5	100.00 % of Total Weight 100.00	0.50
33/EU (31 March 2015) and 2002/53/EC (End- ance with the above EU Directives has been mical substance is absent from the list abov hip Technology Incorporated's knowledge a tration of the chemical substance, if any, is g compounds used by Microchip meet the U at http://ul.com/global/eng/pages/offerings/ii thetive "tubes" in which the specific produ the outer box and certain "reels" may be may hip Technology Incorporated believes the in nductor devices in their original packing may loggy Incorporated cannot guaranteene con I Safety Data Sheets provided by raw mater t have been provided by subcontract assen nd the average weight of anticipated signific	laterials comply wiff of-Life Vehicles (EL n verified via internal ve, the chemical sub und belief as of the d not below the thresi JL94 V0 flammability ndustries/chemicals, ct is shipped are ma ade from PVC plasti formation in this for aterials is true and c mpleteness and accur rial suppliers. Suppli nblers and raw mate cant toxic metals coo	EU Directives: 2002/95/EC (27 January 2003) & design controls, supplier declarations, and /or stance is NOT an intentional ingredient in the s ate of this document, there is no credible reason old of regulatory concern for any regulatory sc standard for plastics. You can access the UL iG 'plastics/ de from polyvinyl chloride (PVC) plastic. "Winde m concerning substances restricted by RoHS in orrect to the best of its knowledge and belief, as uracy of data in this form because it has been ca er information is often protected from disclosur rial suppliers. Information is provided only as et	analytical test of emiconductor of n to believe tha cheme world-wi 2TM family of d ow envelopes" n Microchip Teo s of the date lisi ompiled based re as trade secr stimates of the	data. device and, to t t the unavoidal ide. latabases to ob used to hold th chnology Incor ted in this form on the ranges ets and some ets and some	the best of ble impurity stain a test ne packing porated's n. Microchip provided in information it of these		(mg) Total Gold	Total Wire Bond 7440-57-5 Total Plating on external	100.00 % of Total Weight 100.00 100.00	
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